


MATERIAL DECLARATION SHEET



Material Number	BSDH10S65E6 TO220-2			
Product Line	Semiconductor			
Compliance Date	2023-05-22			
RoHS Compliant	YES	MSL	N.A.	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Carbide	1.74	Silicon Carbide (SiC)	409-21-2	100	0.086	0.086
2	Die Attach	Die Attach	0.06	Diethylene Glycol Monoethyl Ether Acetate	112-15-2	5.6	0.003	0.054
			1.02	Silver (Ag)	7440-22-4	94.4	0.051	
3	Lead Frame	Copper alloy	0.43	Phosphorous (P)	7723-14-0	0.03	0.021	70.413
			1.42	Iron (Fe)	7439-89-6	0.1	0.071	
			1415.16	Copper (Cu)	7440-50-8	99.87	70.321	
4	Mold Compound	Resin	37.38	Phenol Formaldehyde resin (generic)	9003-35-4	6.5	1.857	28.572
			92	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	16	4.572	
			408.25	Silica fused	60676-86-0	71	20.286	
			37.38	Silica-amorphous	7631-86-9	6.5	1.857	
5	Plating	Tin plating	15	Tin (Sn)	7440-31-5	100	0.745	0.745
6	Wire	Pure metal	2.59	Aluminium (Al)	7429-90-5	100	0.129	0.129
Total weight			2012.43 mg					

This Document was updated on: 2023/05/22

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which are exempted from the requirements